



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

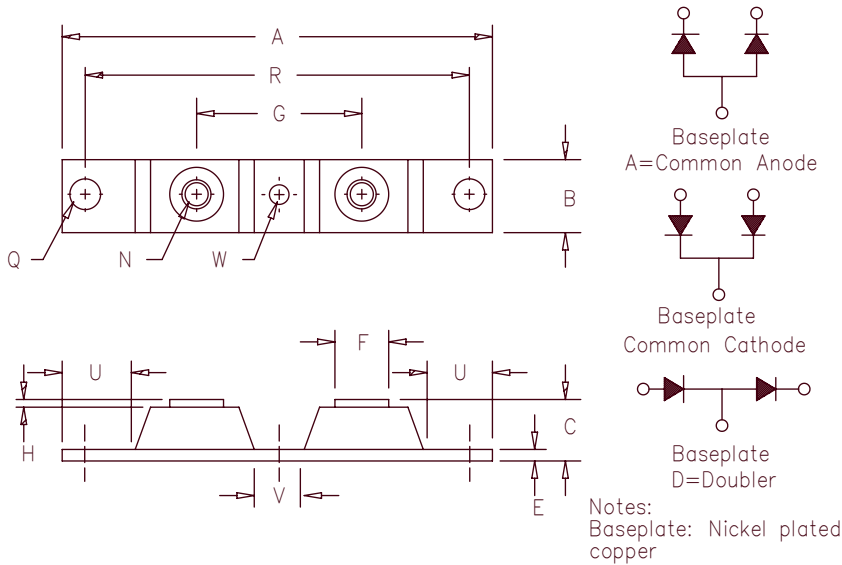
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Schottky PowerMod CPT30060



Dim.	Inches		Millimeters		Notes
	Min.	Max.	Min.	Max.	
A	---	3.630	---	92.20	
B	0.700	0.800	17.78	20.32	
C	---	0.630	---	16.00	
E	0.120	0.130	3.05	3.30	
F	0.490	0.510	12.45	12.95	
G	1.375 BSC		34.92 BSC		
H	0.010	---	0.25	---	
N	---	---	---	---	1/4-20
Q	0.275	0.290	6.99	7.37	Dia.
R	3.150 BSC		80.01 BSC		
U	0.600	---	15.24	---	
V	0.312	.340	7.92	8.64	
W	0.180	0.195	4.57	4.95	Dia.

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage
CPT30060*	MBRP20060CT MBRP30060CT MBR20060CT MBR30060CT	60V	60V

*Add Suffix A for Common Anode, D for Doubler

- Schottky Barrier Rectifier
- Guard Ring Protection
- 300 Amperes/60 Volts
- 175°C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

Electrical Characteristics

Average forward current per pkg	$I_{F(AV)}$ 300 Amps	$T_C = 127^\circ\text{C}$, Square wave, $R_{\theta JC} = 0.20^\circ\text{C/W}$
Average forward current per leg	$I_{F(AV)}$ 150 Amps	$T_C = 127^\circ\text{C}$, Square wave, $R_{\theta JC} = 0.40^\circ\text{C/W}$
Maximum surge current per leg	I_{FSM} 2000 Amps	8.3ms, half sine, $T_J = 175^\circ\text{C}$
Maximum repetitive reverse current per leg	$I_{R(OV)}$ 2 Amps	$f = 1 \text{ KHZ}$, 25°C , $1\mu\text{sec}$ square wave
Max peak forward voltage per leg	V_{FM} .82 Volts	$I_{FM} = 200\text{A}; T_J = 25^\circ\text{C}^*$
Max peak forward voltage per leg	V_{FM} .68 Volts	$I_{FM} = 200\text{A}; T_J = 175^\circ\text{C}^*$
Max peak reverse current per leg	I_{RM} 75 mA	$V_{RRM}, T_J = 125^\circ\text{C}^*$
Max peak reverse current per leg	I_{RM} 4.0 mA	$V_{RRM}, T_J = 25^\circ\text{C}$
Typical junction capacitance per leg	C_J 4300 pF	$V_R = 5.0\text{V}, T_C = 25^\circ\text{C}$

*Pulse test: Pulse width 300 μsec , Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temp range	T_{STG}	-55°C to 175°C
Operating junction temp range	T_J	-55°C to 175°C
Max thermal resistance per leg	$R_{\theta JC}$	0.40°C/W Junction to case
Max thermal resistance per pkg	$R_{\theta JC}$	0.20°C/W Junction to case
Typical thermal resistance (greased)	$R_{\theta CS}$	0.08°C/W Case to sink
Terminal Torque		35-50 inch pounds
Mounting Base Torque (outside holes)		30-40 inch pounds
Mounting Base Torque (center hole)		8-10 inch pounds
center hole must be torqued first		
Weight		2.8 ounces (75 grams) typical

CPT30060

Figure 1
Typical Forward Characteristics – Per Leg

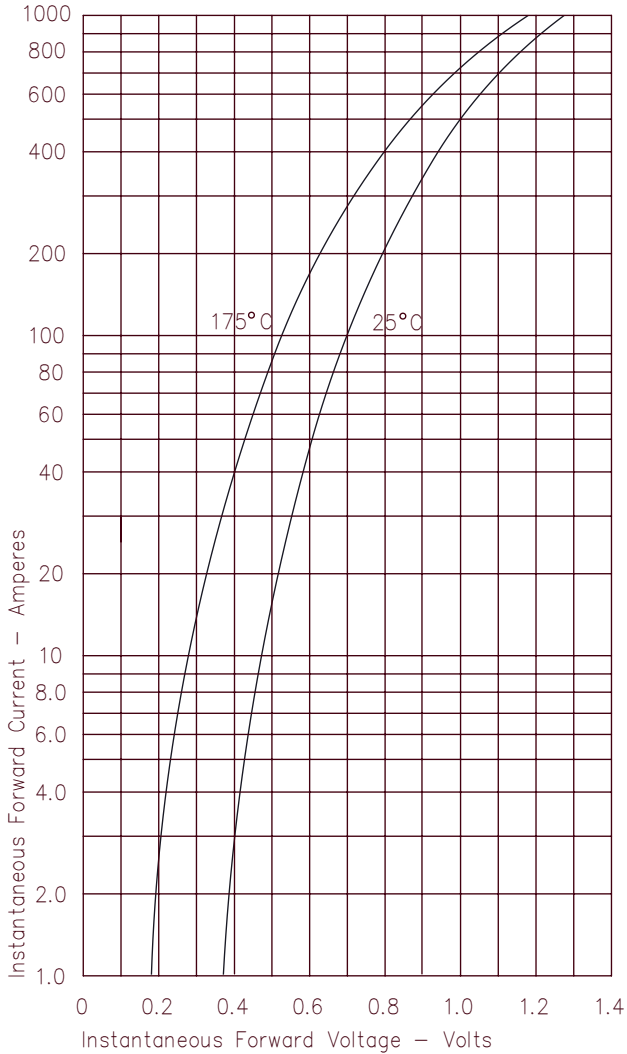


Figure 3
Typical Junction Capacitance – Per Leg

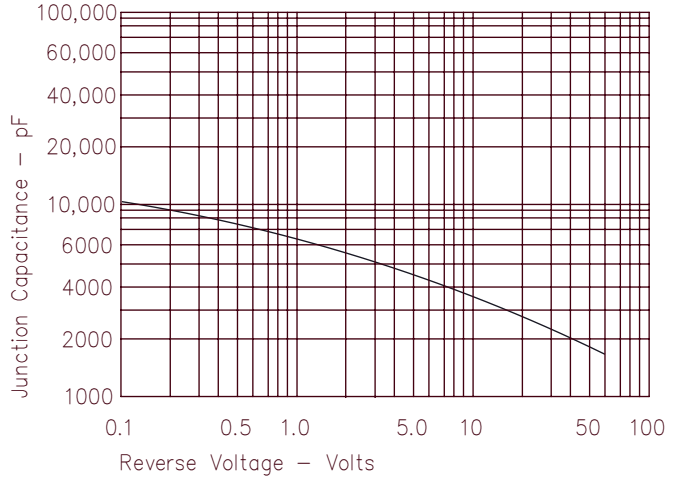


Figure 4
Forward Current Derating – Per Leg

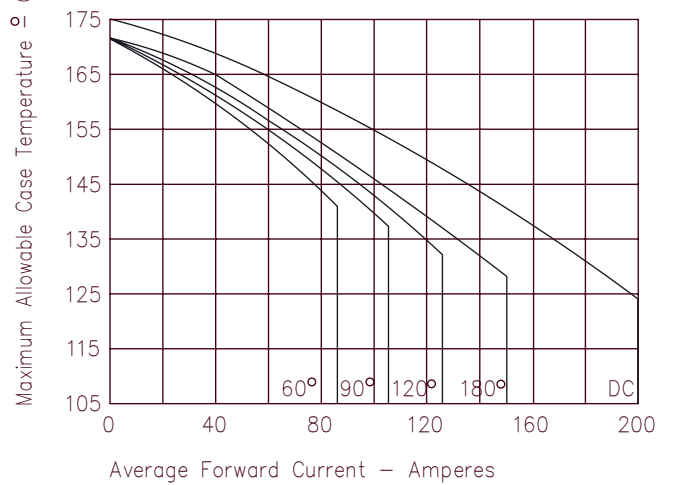


Figure 2
Typical Reverse Characteristics – Per Leg

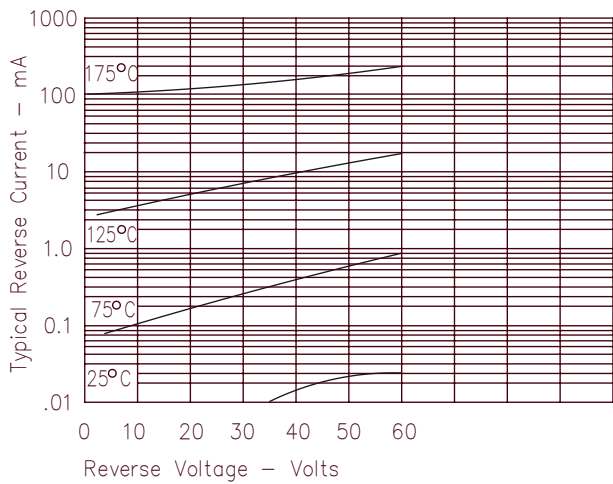
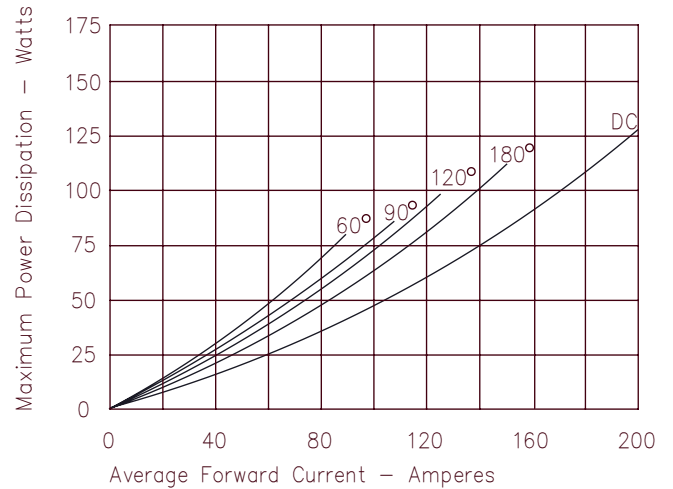


Figure 5
Maximum Forward Power Dissipation – Per Leg



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